SUSS MICROTEC INVESTOR PRESENTATION

April 2014

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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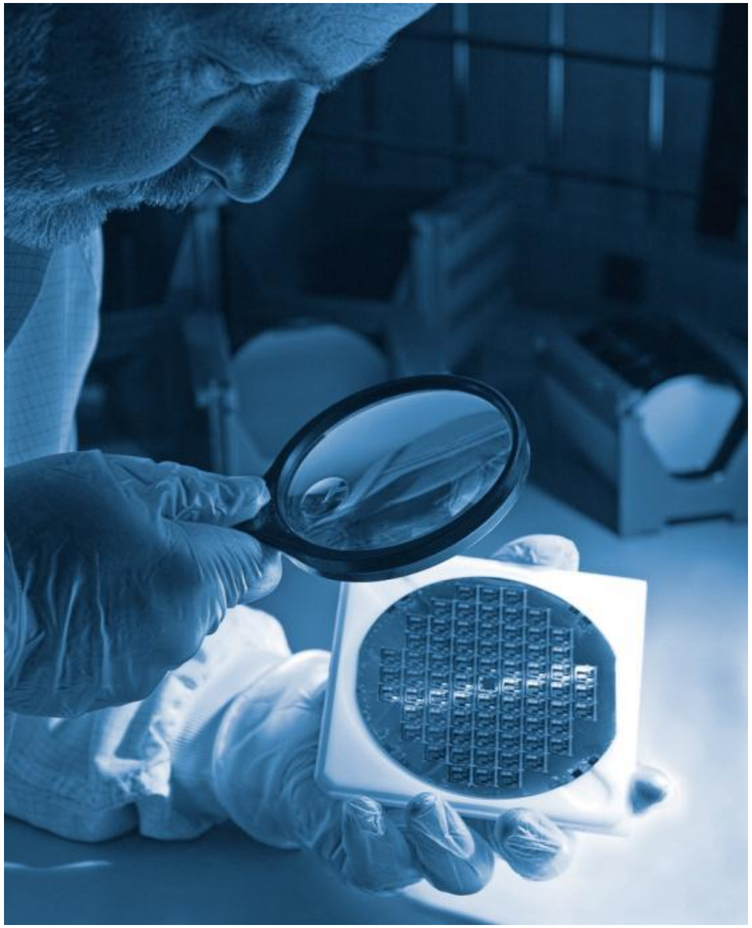
SUSS MICROTEC AT A GLANCE

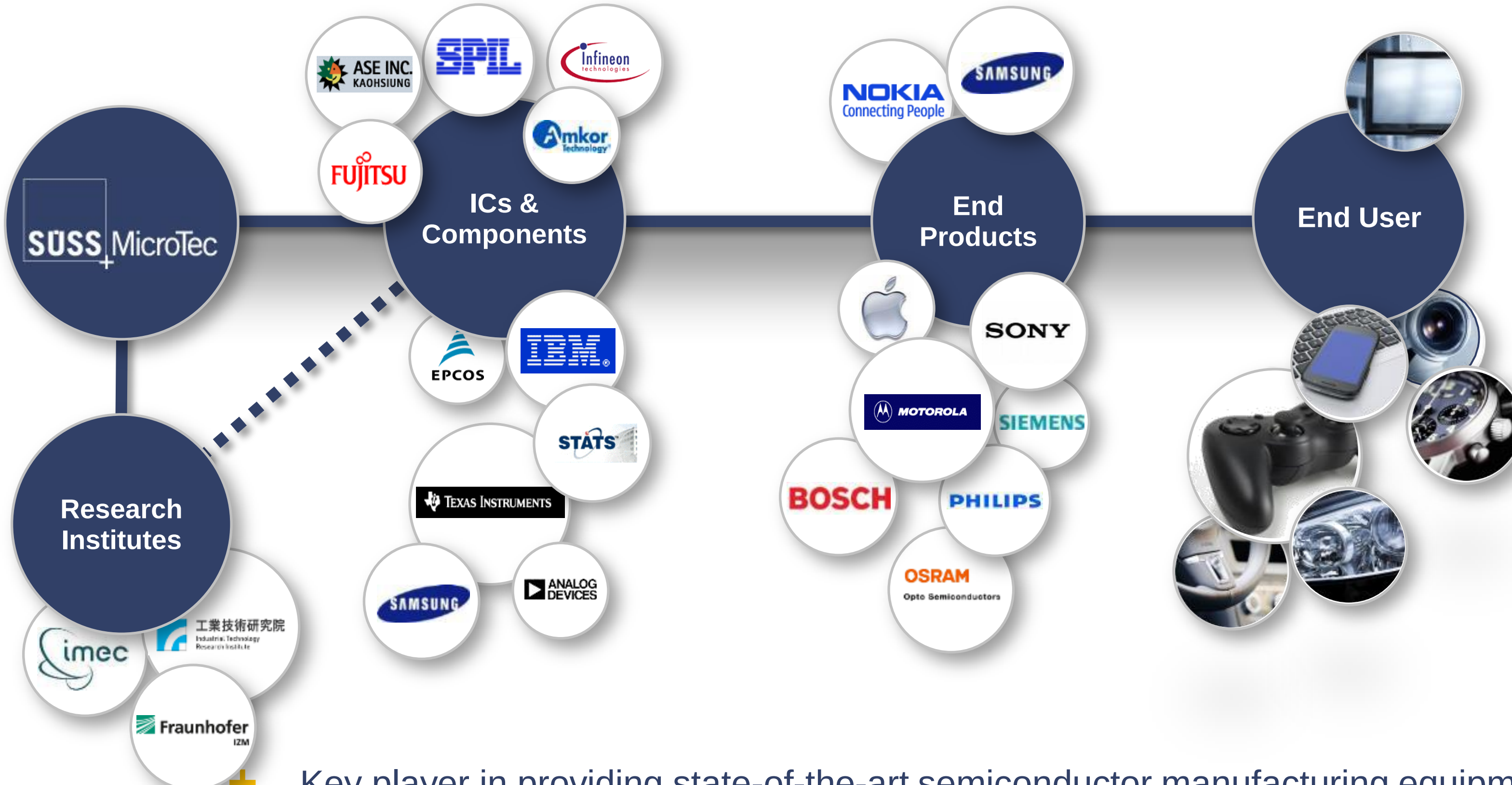
- SUSS MicroTec: A global leader in semiconductor equipment
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- We are focused on high growth market segments: Semiconductors, MEMS, LEDs



- Key Data:
  - Stock Exchange Symbol: SMHN
  - Share price*: 6.98 €
  - Market Cap*: 133 € million
  - Net Cash, December 31, 2013: 35.7 € million

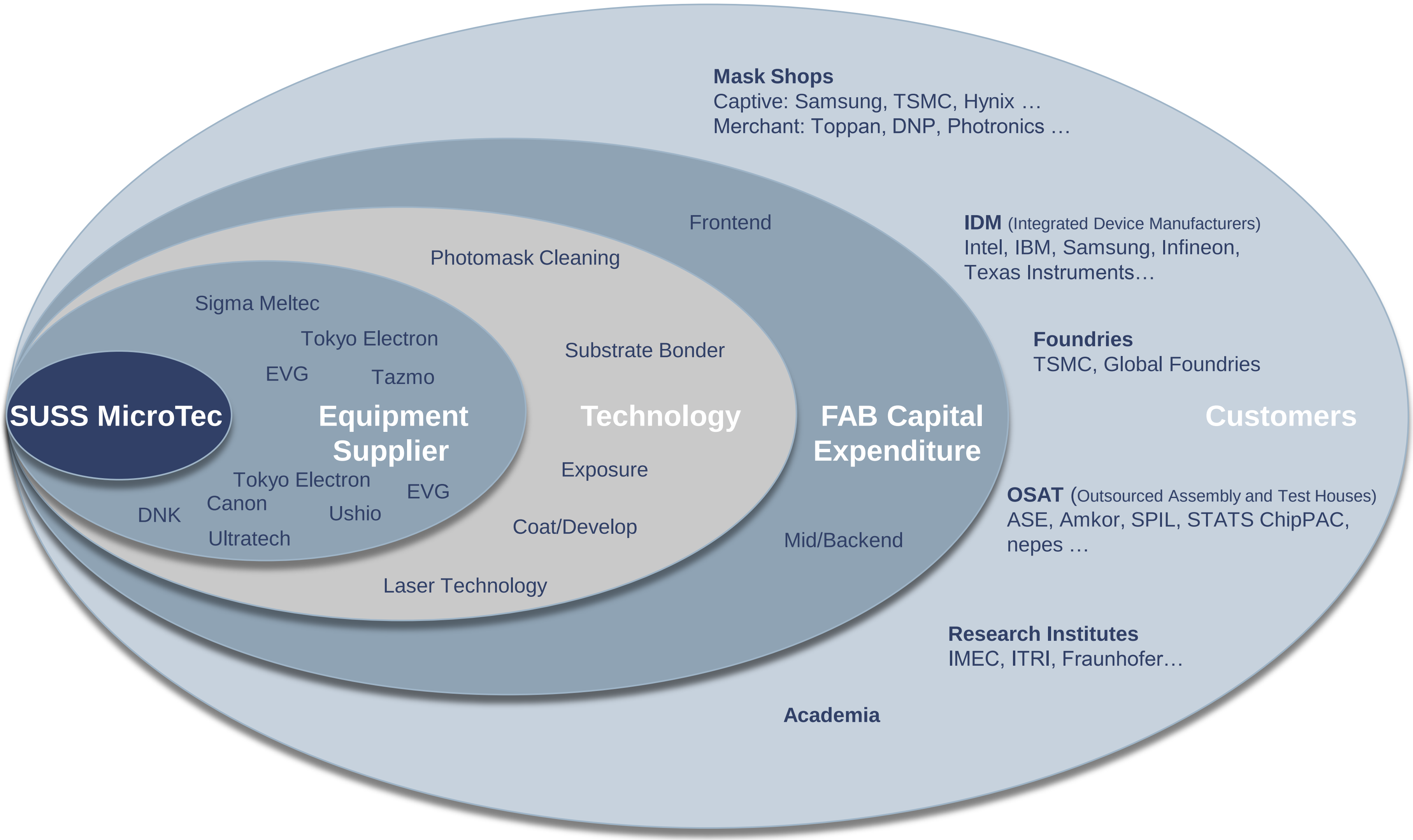
* March 28, 2014

SUSS MICROTEC IN THE VALUE CHAIN

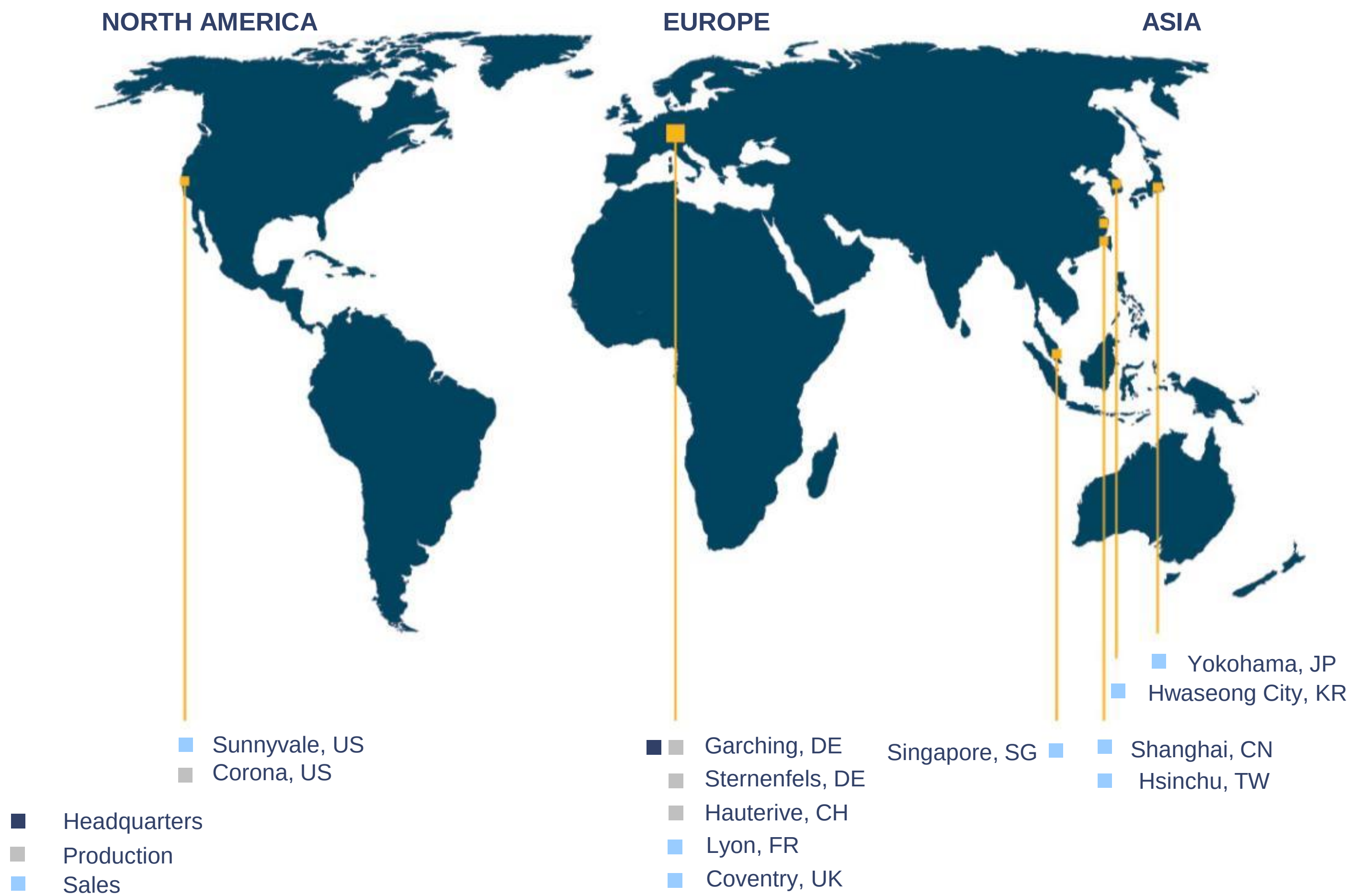


- Key player in providing state-of-the-art semiconductor manufacturing equipment
- Development of highly innovative process solutions with industry and R&D partners
- Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec’s equipment

THE SEMICONDUCTOR MARKET



SUSS MICROTEC – A GLOBAL PLAYER



MAIN PRODUCTION SITES

Germany

Garching*

+ SUSS MicroTec HQ
+ Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
+ Core competencies:
  - **Exposure** (proximity exposure)
  - **Alignment**

Sternenfels*

+ Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
+ Core competencies:
  - **Wet processing**
  - **Wafer bonding**

USA

Corona**

+ Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
+ Core competencies:
  - **Exposure** (UV projection lithography)
  - **Laser Ablation**

* Production site owned by SUSS MicroTec
** Production sited rented by SUSS MicroTec

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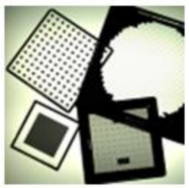
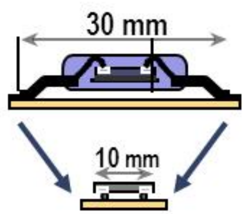
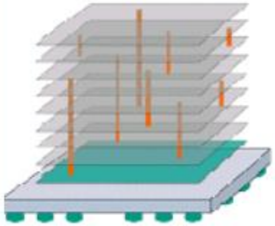
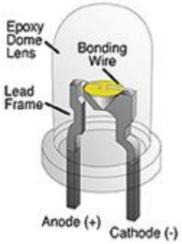
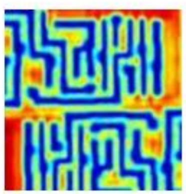
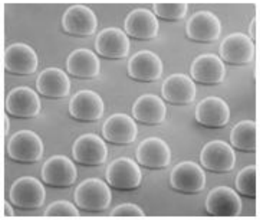
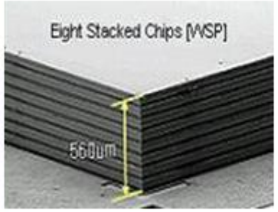
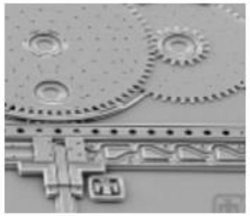
Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	**Advanced Packaging** Micro-Bumping	**3D Integration/Stacking**	**MEMS** Computing, Automotive, Medical Applications …	**LED** General Lighting, HB and UHB LED
				
				

SEGMENTS, PRODUCTS AND MARKETS

SÜSS MicroTec

Segments	Photomask Equipment	Lithography			Substrate Bonder
Products	 MaskTrack Pro	 Exposure Systems		 Coater/Developer	 Wafer Bonder
	Frontend	Mid- and Backend			
Process Steps	Photomask Cleaning	Stepper, Scanner (UV projection) Laser Ablation	Mask Aligner (proximity exposure) Nano Imprinting	Coating Developing	Bond Alignment Permanent Bonding Temporary Bonding
Key figures 2013	Sales: 18.4 € million EBIT: 1.6 € million	Sales: 88.3 € million EBIT: 3.2 € million			Sales: 22.8 € million EBIT: -21.7 € million

Markets

- Mask Manufacturing
- Advanced Packaging
- 3D Integration
- MEMS
- LED

RESTRUCTURING OF PERMANENT BONDING

+ **Reevaluation of the business situation in permanent bonding**
  - ongoing losses
  - expansion of the restructuring measures, which have been taken in Q2, 2013

Cease production of cluster systems for permanent bonding applications

+ **Losses of the Substrate Bonding Division will be reduced significantly**

+ **The successful manual permanent bonding systems are not affected**

+ **One-off expense of € 8.3 million was taken in Q4 2013:**
  - € 6.7 million for write-offs on raw materials, unfinished goods and demonstration tools
  - € 1.6 million for precautionary formed accruals for single customer projects

+ **Total expense for the restructuring of the permanent bonding in 2013 amounts to € 13.2 million**

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TECHNOLOGY EVOLUTION

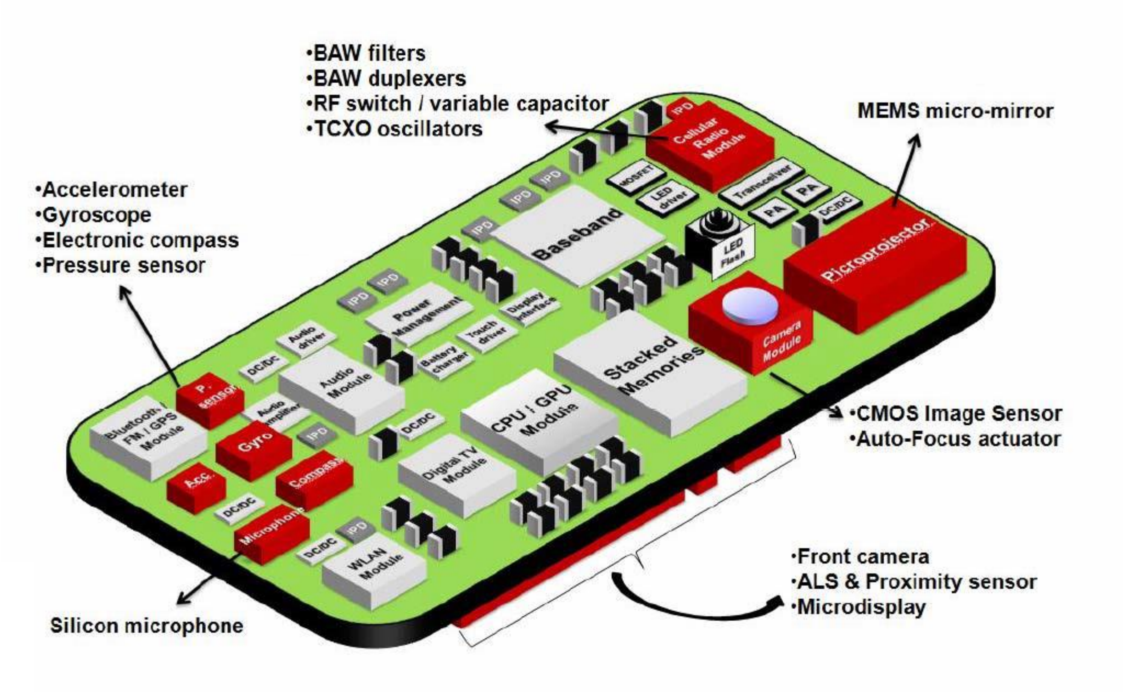
~1985...today

~1987...today

~1910...today

~1950...today

GROWTH DRIVER SMARTPHONES AND TABLETS



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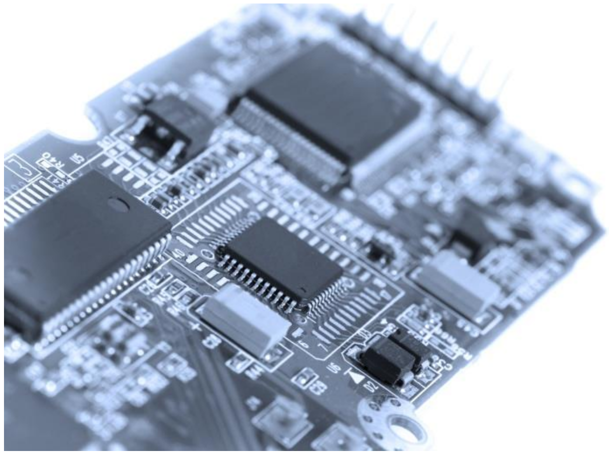


MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle	- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media - Mobile devices like smartphones and tablet PCs provide this capability at affordable cost - New device generations offer higher functionality	
E-Mobility	- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios - EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs	
Energy Efficiency	- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting - Energy efficiency in industrial production - Smart energy management in household applications safes energy	

EXPECTED MARKET DEVELOPMENTS

With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging	Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets
3D Integration (TSV)	Transition to production volume in the years to come
Compound Semiconductors	LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

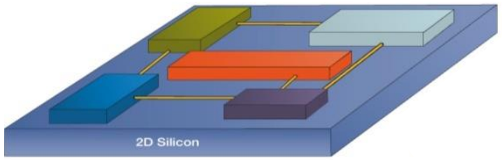
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple pattering allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

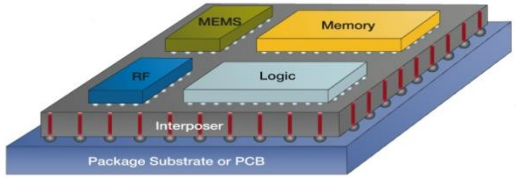
2.5D Packaging

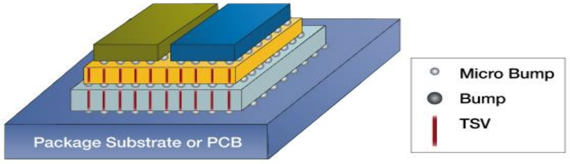
- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore‘s Law

3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore“
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption







SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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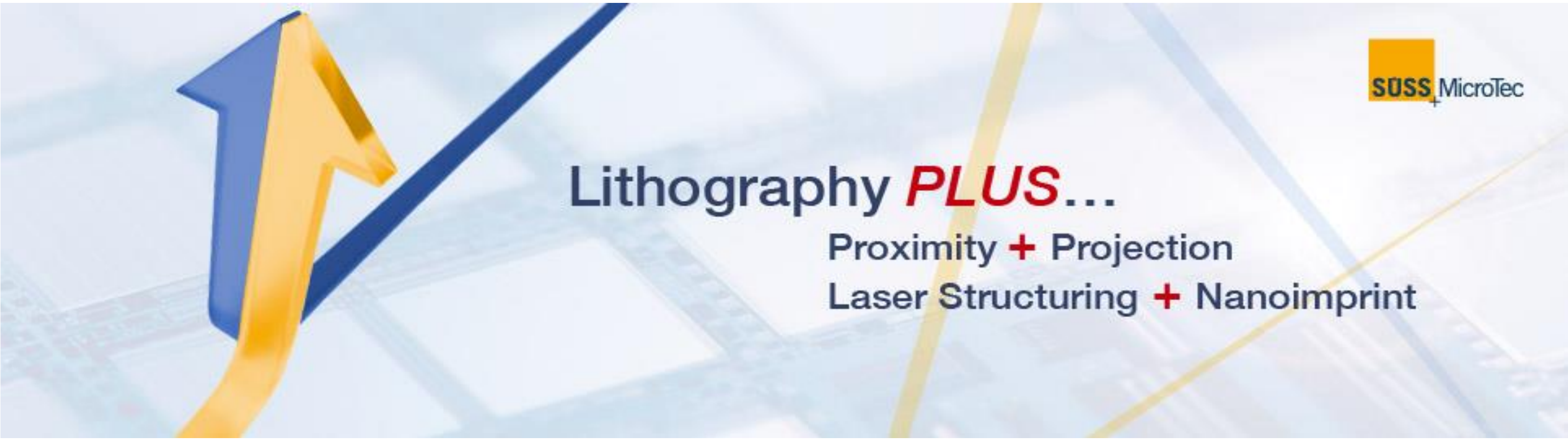
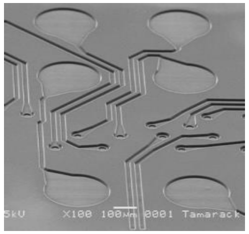
LITHOGRAPHY COMPETENCY

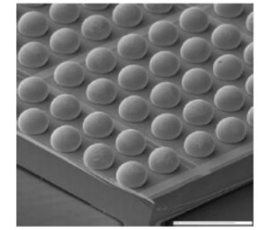
+ Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
+ **Not one single exposure technology fits all needs at the same time**
+ The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
+ SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements



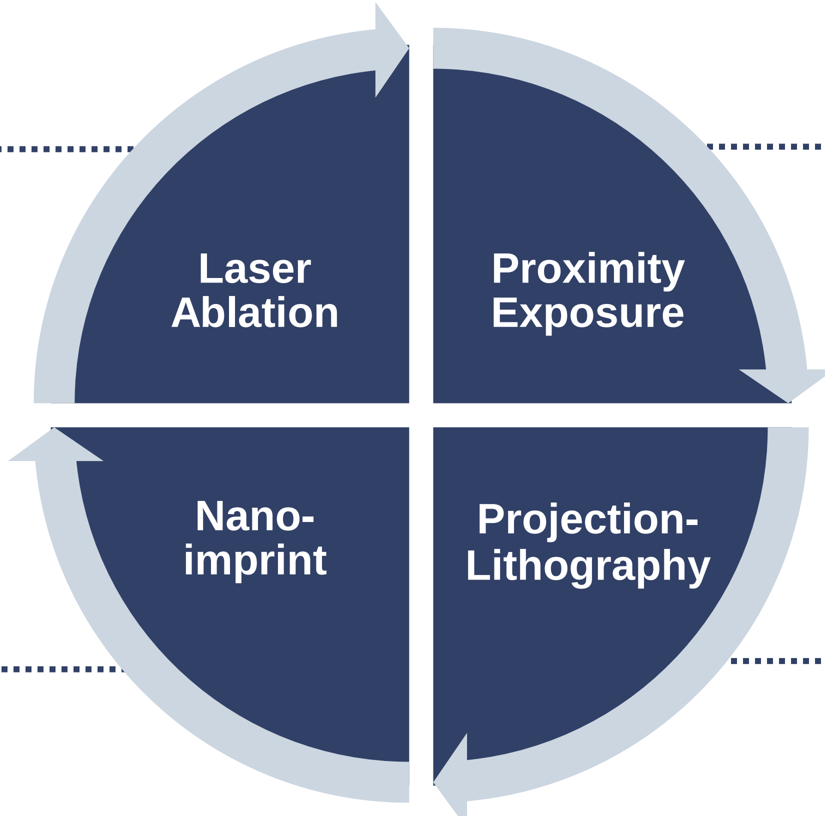
EXPOSURE SOLUTIONS



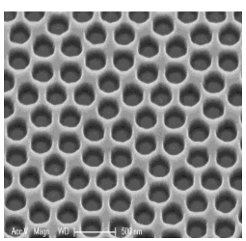
WLCSP:
Fanout WLP



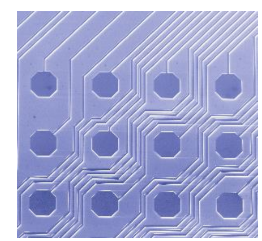
Flip Chip:
Solder Bumping



LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



+ Only SUSS MicroTec offers complete exposure solutions for the mid-/back-end

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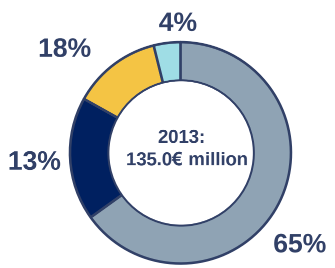
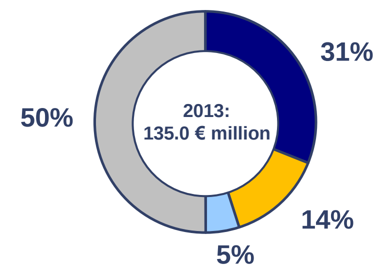
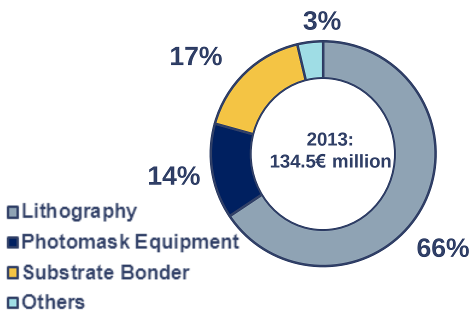
Order Entry by Segment



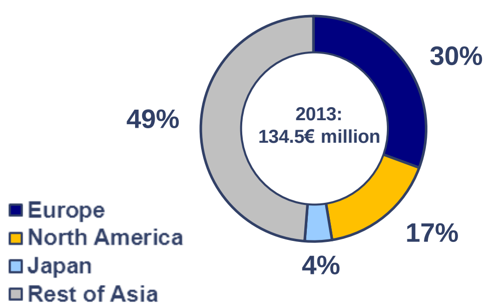
Order Entry by Region



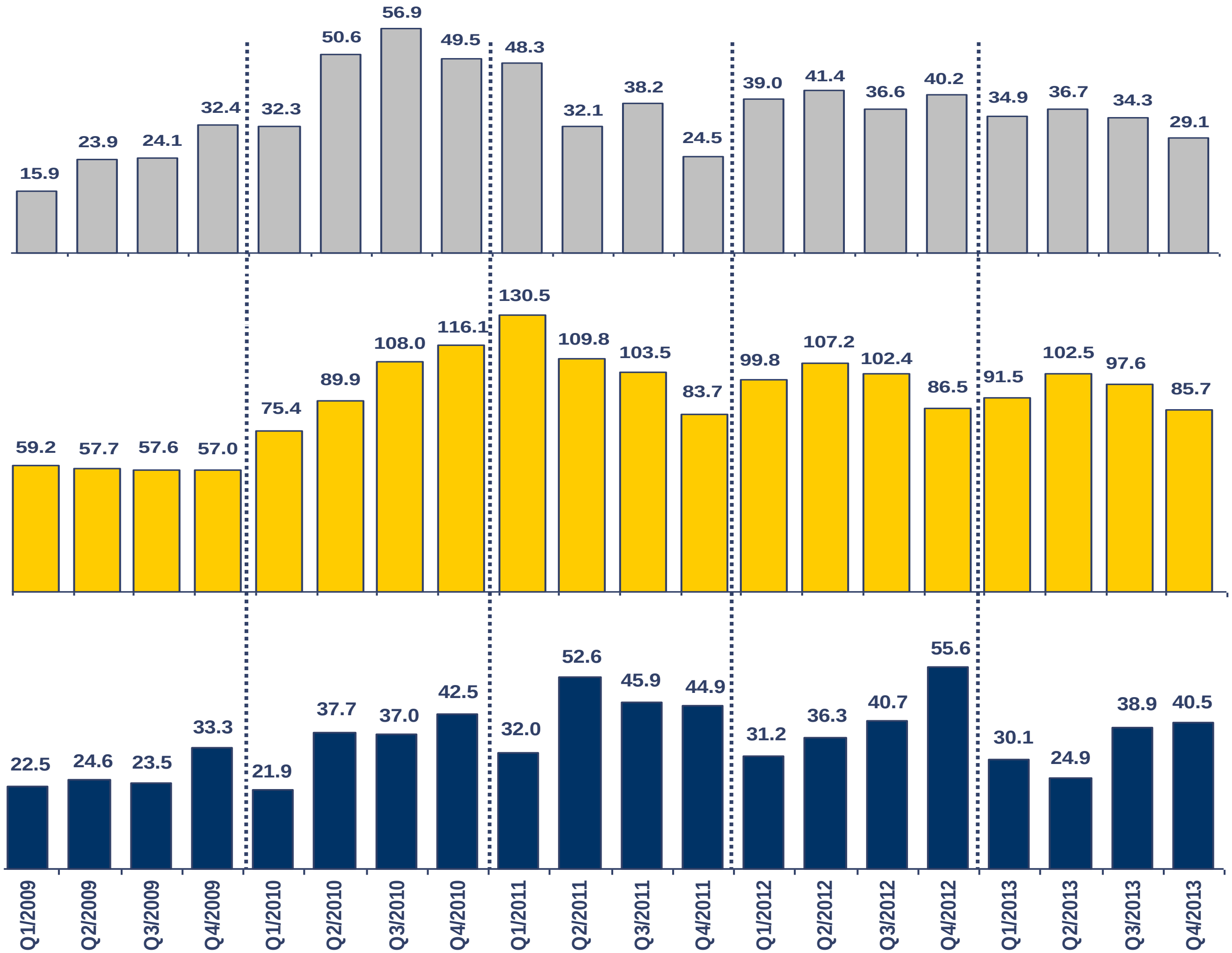
Sales by Segment



Sales by Region



LONG TERM BUSINESS DEVELOPMENT

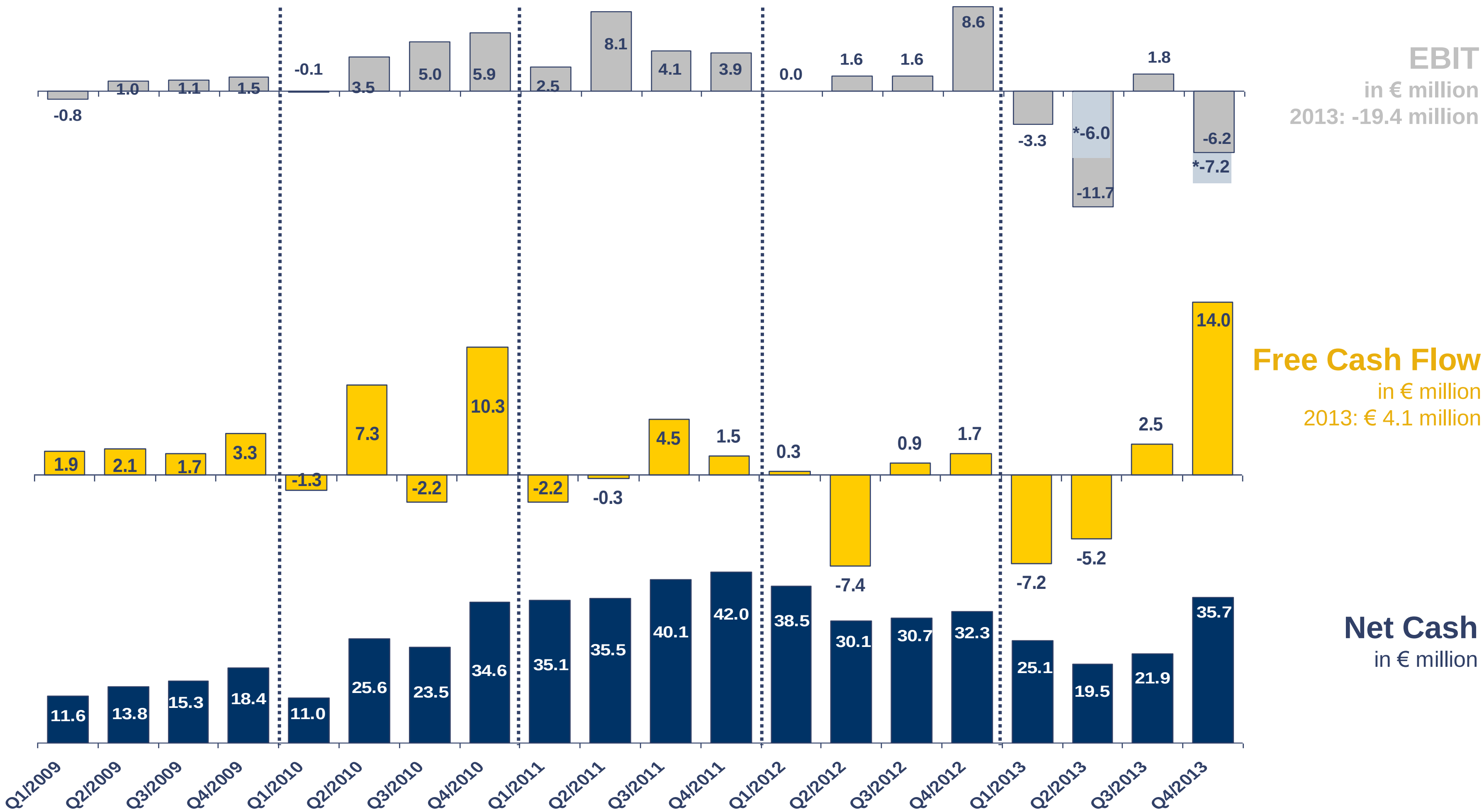


Order Entry
in € million
2013: € 135 million

Order Backlog
in € million

Sales
in € million
2013: € 135 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effects from restructuring of the product line permanent bonding

KEY FINANCIALS

in € million	2013	2012	in %
Order Intake	**135.0**	**157.2**	**-14.1%**
Order Backlog 12/31	**85.7**	**86.5**	**-0.9%**
Revenue	**134.5**	**163.8**	**-17.9%**
EBIT	**-19.4**	**11.7**	**--**
EBIT in % of Sales	*-14.4%*	*7.6%*	*-21.5%pt.*
Earnings after tax (continuing operations)	**-16.0**	**7.6**	**--**
Earnings after tax	**-16.0**	**9.1**	**--**
EPS in € (continued op.)	**-0.84**	**0.40**	**--**
Net Cash*	**35.7**	**32.3**	**+10.5%**
Free Cash Flow**	**4.1**	**-4.5**	**--**
Employees 12/31	**655**	**704**	**-7.0%**

* incl. stock of interest-bearing securities
** before consideration of purchased interest-bearing securities , the acquisition of Tamarack Scientific and the gain out of the sale from the Test Business

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SUMMARY AND OUTLOOK

2013: - Milestone achievement in temporary bonding
- Restructuring of product line Permanent Bonding expanded
- Further integration of SUSS MicroTec Photonic Systems

Fundamental growth in target markets

Strong competitive positioning: first or second in the target markets

Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”

Outlook

FY 2014: - Sales of 135 - 145 € million
- EBIT: -5 to 0 € million

Q1 2014: - Order Intake 25 - 35 € million

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INVESTOR RELATIONS INFORMATION

SÜSS MicroTec

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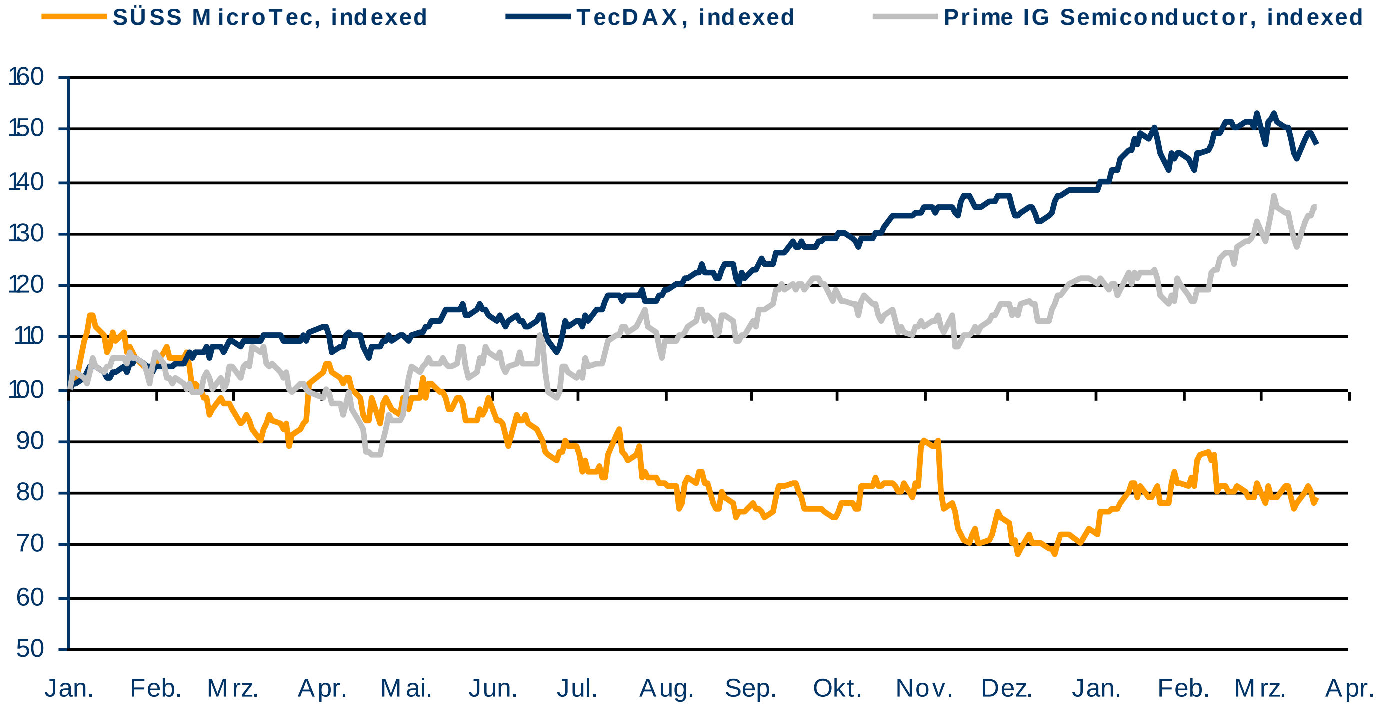
Financial Calendar 2014

Annual Report 2013	28 Mar
Quarterly Report 2014	8 May
Berenberg Investment Conference Paris	22 May
Deutsche Bank Investment Conference, Berlin	12 - 13 Jun
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	17 Jun
Interim Report 2014	7 Aug
Nine-month Report 2014	6 Nov
German Equity Forum 2014, Frankfurt am Main	24 - 26 Nov

STOCK PERFORMANCE: JANUARY 2013 – MARCH 2014

(Price of the SUSS MicroTec Share at January 2, 2013: 8.85 €)



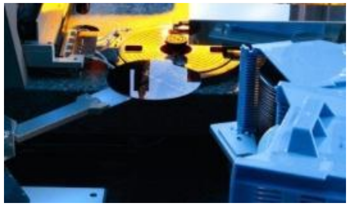
Average daily trading volume January 2013 – March 2014: ~ 103,000

SUSS MICROTEC PRODUCT PORTFOLIO

Photomask Equipment

Coater/Developer

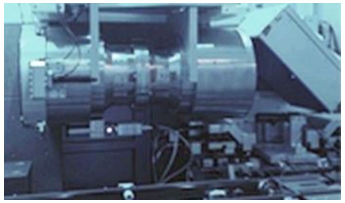
Wafer Bonders



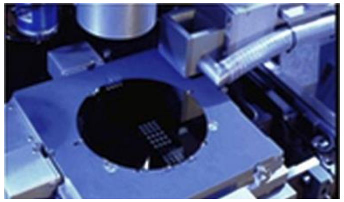
Alignment Verification Systems

Mask Aligners

Imprinting Systems



UV-Projection Stepper / Scanner



Excimer Laser Systems